



## DEFENSE LOGISTICS AGENCY

LAND AND MARITIME  
POST OFFICE BOX 3990  
COLUMBUS, OH 43218-3990

September 2<sup>nd</sup>, 2025

Mario Saucedo  
General Manager  
Micross STS (Hi-Reliability Microelectronics)  
1804 McCarthy Blvd  
Milpitas, CA 95035

Dear Mr. Saucedo:

Re: Laboratory Suitability Status for Class Q and V assembly/test flow; MIL-STD-883;  
FSC 5962; VQC-25-039764; Abel. CN: 092849.

Micross (Silicon Turnkey Solutions) has demonstrated compliance to MIL-STD-883, the test standard for integrated circuits, to the DLA Land & Maritime. This letter is revised to reflect the status of Micross (Silicon Turnkey Solutions) Laboratory Suitability, for the test methods and conditions shown in the enclosure. All testing on monolithic microcircuits shall be performed in accordance with the requirements of military specification MIL-PRF-38535 effective immediately. This letter supersedes DLA Land and Maritime-VQC-20-034893 to reflect the current suitability status.

This laboratory suitability is subject to the policies, procedures, and conditions of the Defense Standardization Program, as published in the manual DoD 4120.24-M and SD-6.

Micross (Silicon Turnkey Solutions) and QPL/QML test labs shall notify the qualifying activity immediately after learning of a potential issuance of a GIDEP alert, problem advisory, or major quality/reliability problem on their QPL/QML products utilizing test methods listed on the enclosure. Failure to provide prior notification may be grounds for removal from QML-38535.

This Laboratory Suitability is valid until terminated by written notice from DLA Land and Maritime. If warranted, it may be withdrawn by DLA Land and Maritime at any time. Each of these facilities is subject to an audit by the Qualifying Activity with minimum notice.

If you have any questions, please contact Mr. Jerrod Abel at (614) 692-9933.

Sincerely,

MICHAEL S. ADAMS

Chief

Custom Devices Branch

Enclosure

<u>Test</u>	<u>Method/Condition</u>	<u>Micross (STS)</u>	<u>Subcontractors</u>
Moisture Resistance	1004	X	
Steady State Life Test	1005 (A-F)	X	
Salt Atmosphere	1009 (A)	X	
Temperature Cycling	1010 (C)	X	
Thermal Shock	1011 (B)	X	
Seal	1014 (A <sub>1</sub> , A <sub>2</sub> , C <sub>1</sub> )	X	
Burn-in	1015 (A-F)	X	
Internal Gas Analysis	1018		EAG
Constant Acceleration	2001 (D-E, Y1 Only)	X	
Mechanical Shock	2002 (B)	X	
Solderability	2003 (Test A-C)	X	
Lead Integrity	2004 (A, A <sub>1</sub> , B <sub>1</sub> , B <sub>2</sub> , D, E)	X	
Vibration, Variable Frequency	2007 (A)	X	
External Visual	2009	X	
Internal Visual	2010 (A, B)	X	
Bond Strength	2011 (D)	X	
Radiography	2012	X	
DPA	2013	X	
Internal Visual & Mechanical	2014	X	
Resistance to Solvents	2015	X	
Physical Dimensions	2016	X	
Die Shear Strength	2019	X	
PIND	2020 (A)	X	
Nondestructive Bond Pull	2023	X	
Adhesion of Lead Finish	2025	X	
Substrate Attach Strength	2027	X	
CSAM	2030	X	
Resistance to Soldering Heat	2036	X	
Solder Column Pull	2038	X	
ESDS Classification	3015	X	
Electrical Test	Device Specification	X	

**Subcontractors:**

Eurofins EAG Materials Science (EAG)  
 103 Commerce Blvd.  
 Liverpool, NY 13088